INTERPACK 2021 SCHEDULE-AT-A-GLANCE

Pacific Time		Type	Moderators & Speakers	Title	Company
Day 1 - Tuesday, 26th October 2021					
7:45 AM	8:00 AM	Welcome	Thomas Costabile (ASME Executive Director/CEO)	Welcome to ASME InterPACK 2021 Virtual Event	ASME
Room 1: Keynote Session Chaired by Kaushik Mysore, AMD (Introduction and Q&A)					
8:00 AM	8:50 AM	Keynote	Ephraim Suhir	Avoiding Inelastic Strains in Solder Joint Interconnections of IC Packages	Portland State University
8:50 AM	9:00 AM	Q&A			
9:00 AM	9:10 AM	Break	Coffee Break / Exhibitor Corner		
Panel Sessions					
Room 1: Chaired by Gamal Refai-Ahmed (Xilinx)					
9:10 AM	10:30 AM	Panel	Gamal Refai-Ahmed	Thermo-Mechanical Challenges from Package to System to Maximize Silicon Performance	Xilinx
10:30 AM	10:40 AM	Q&A			
Room 2: Chaired by Fang Luo (State University of New York, Stony Brook)					
9:10 AM	10:30 AM	Panel	Fang Luo	Potential of Additive Manufacturing for Power Electronics	State University of New York, Stony Brook
10:30 AM	10:40 AM	Q&A			
Room 3: Chaired by: Yoonjin Won (University of California, Irvine)					
9:10 AM	10:10 AM	Panel	Yoonjin Won	Issues, Challenges, and Future Opportunities about Nanomaterials Integration into Large Systems	University of California, Irvine
10:10 AM	10:40 AM	Q&A			
10:40 AM	10:50 AM	Break	Coffee Break / Exhibitor Corner		
Panel Sessions					
Room 1: Chaired by Dereje Agonafer (University of Texas at Arlington)					
10:50 AM	12:10 PM	Panel	Dereje Agonafer	Industrial Considerations for Data Center Thermal Management	University of Texas at Arlington
12:10 PM	12:20 PM	Q&A			
Room 2: Chaired by Victor Chiriac (Global Cooling Technology Group)					
10:50 AM	12:10 PM	Panel	Victor Chiriac	Thermal Challenges of Advanced Mobile/Telecom/Wireless and Computing Devices	Global Cooling Technology Group
12:10 PM	12:20 PM	Q&A			
Room 3: Chaired by Nenad Miljkovic (University of Illinois Urbana-Champaign)					
10:50 AM	12:10 PM	Panel	Nenad Miljkovic	Additive Manufacturing for Cooling and Thermal Storage in Electronics Thermal Management	University of Illinois Urbana-Champaign
12:10 PM	12:20 PM	Q&A			
12:20 PM	1:50 PM	Break	Lunch Break / Exhibitor Corner		
Room 1: Tutorial Chaired by Jin Yang (Intel)					
1:50 PM	3:40 PM	Tutorial	Abhijit Dasgupta, SB Park	Reliability of Heterogeneous Integration (HI) Systems	University of Maryland, State University of New York, Binghamton
3:40 PM	3:50 PM	Q&A			
Room 2: Tutorial Chaired by Jimil Shah (TMGCORE)					
1:50 PM	3:40 PM	Tutorial	Ryan J. Lewis, Y. C. Lee	Thermal Designs Using Vapor Chambers for Smartphones, Laptops, HPC and Power Electronics	Kelvin Thermal
3:40 PM	3:50 PM	Q&A			
3:50 PM	4:00 PM	Break	Coffee Break / Exhibitor Corner		
Room 1: Industry, National Laboratory, and Academia Posters - Chaired by Solomon Adera (University of Michigan)					
4:00 PM	6:00 PM	GatherTown	Poster Presentations and Q&A		
InterPACK Organization Zoom Meeting					
4:00 PM	5:00 PM	ASME EPPD Executive Committee Meeting (By Invitation Only)			
Day 2 - Wednesday, 27th October 2021					
7:45 AM	8:00 AM	ASME EPPD	Kaushik Mysore	ASME EPPD Introduction	AMD
Room 1: Keynote Session Chaired by Kaushik Mysore (AMD)					
8:00 AM	8:50 AM	Keynote	Samuel Graham	Developing Wide Bandgap Electronics for Future Power and RF Applications	University of Maryland
8:50 AM	9:00 AM	Q&A			
9:00 AM	9:10 AM	Break	Coffee Break / Exhibitor Corner		
Panel Sessions					
Room 1: Chaired by Michael Fish (Army Research Laboratory)					

Start	End	Type	Speaker	Title	Affiliation
9:10 AM	10:30 AM	Panel	Michael Fish	Cryogenic Cooling of Solid State Devices	Army Research Laboratory
10:30 AM	10:40 AM	Q&A			
Room 2: Chaired by John Thome (JJ Cooling)					
9:10 AM	10:30 AM	Panel	John Thome	Two-Phase Cooling Systems for High Power Electronics/Data Centers	JJ Cooling
10:30 AM	10:40 AM	Q&A			
10:40 AM	10:50 AM	Break	Coffee Break / Exhibitor Corner		
Room 1: Tutorial Chaired by Adam Wilson (Army Research Laboratory)					
9:10 AM	11:00 AM	Tutorial	Casper Andreasen, Joe Alexandersen	Additive Manufacturing and Topology Optimization Methods for Thermal Management	Technical University of Denmark, University of Southern Denmark
11:00 AM	11:10 AM	Q&A			
Room 2: Chaired by: Michael H. Azarian (CALCE, University of Maryland College Park)					
10:50 AM	12:10 PM	Panel	Michael H. Azarian	Artificial Intelligence and Reliability: Future Opportunities	CALCE, University of Maryland College Park
12:10 PM	12:20 PM	Q&A			
Room 3: Chaired by Anna Prakash (Intel Corporation)					
10:50 AM	12:10 PM	Panel	Anna Prakash	Women in Engeering	Intel Corporation
12:10 PM	12:20 PM	Q&A			
12:20 PM	1:20 PM	Presenter and Award Winner	**Room 1: Avram Bar Cohen Memorial Award Presentation by Ricky Lee Chaired by Baris Dogruoz (Maxar Technologies)**		
1:20 PM	1:40 PM	Q&A			
1:40 PM	1:50 PM	Break	Coffee Break / Exhibitor Corner		
Room 1: Tutorial Chaired by Michael H. Azarian (CALCE, University of Maryland College Park)					
1:50 PM	3:40 PM	Tutorial	Ephraim Suhir	Thermal Stress Failures in Electronic Packaging: Prediction and Prevention	Portland State University
3:40 PM	3:50 PM	Q&A			
Room 2: Tutorial Chaired by Gilberto Moreno (NREL)					
1:50 PM	3:40 PM	Tutorial	Paul Paret	Boned Interface Materials for High Temperature, Wide-bandgap Power Electronic Devices	National Renewable Energy Laboratory
3:40 PM	3:50 PM	Q&A			
3:50 PM	4:00 PM	Break	Coffee Break / Exhibitor Corner		
Workshop Session Chaired by Anna Prakash (Intel Corporation)					
4:00 PM	6:00 PM	Workshop	Anna Prakash	Introduction to Robotics, AI and Intel's OpenVINO toolkit ™	Intel Corporation
6:00 PM	6:15 PM	Q&A			
InterPACK Organization Zoom Meeting					
6:00 PM	7:00 PM	K-16 Committee Meeting			
Day 3 - Thursday, 28h October 2021					
6:30 AM	7:30 AM	InterPACK		JEP Meeting	Hong Kong University of Science and Technology
7:45 AM	8:00 AM	ASME EPPD	Kaushik Mysore	ASME EPPD Introduction	AMD
Room 1: Keynote Session Chaired by Kaushik Mysore (AMD)					
8:00 AM	8:50 AM	Keynote	Jessica Gullbrand	Liquid Cooling of IT Equipment	Intel
8:50 AM	9:00 AM	Q&A			
9:00 AM	9:10 AM	Break	Coffee Break / Exhibitor Corner		
Workshop Sessions					
Room 1: Chaired by Saket Karajgikar (Facebook)					
9:10 AM	10:30 AM	Workshop	Saket Karajgikar, Jimil M. Shah	Career Development Workshop	Facebook, TMGcore
10:30 AM	10:40 AM	Q&A			
Room 2: Moderated by Kaushik Mysore (AMD), SB Park (University of New York, Binghamton)					
9:10 AM	10:30 AM	Workshop	(1) Bahgat Sammakia, Ganesh Subbarayan, Kamal Sikka (2) Bryan Black	HIR Workshop - Part 1 (1) Federal Incentives & partnership with Academia & Industry to strengthen US Semiconductor Technology Leadership (2) Future Vision of Electronics Packaging	(1) Binghamton University, Purdue University, IBM (2) AMD
10:30 AM	10:40 AM	Q&A			

10:40 AM	10:50 AM	Break	Coffee Break / Exhibitor Corner		
Workshop Sessions					
Room 1: Chaired by Ronald Warzoha (K-16 Committee)					
10:50 AM	12:10 PM	Workshop	Luca Amalfi, Ashutosh Giri	K-16 Mentoring Workshop	Nokia/Bell Labs, University of Virginia
12:10 PM	12:20 PM	Q&A			
Room 2: Moderated by Kaushik Mysore (AMD), SB Park (University of New York, Binghamton)					
10:50 AM	12:10 PM	Workshop	William Chen William Bottoms	HIR Workshop - Part 2 Heterogeneous Integration Roadmap: Drivers & Ramifications of Strengthening US Semiconductor R&D, Manufacturing Ecosystem & Industrial Base	ASEUS, 3MTS
12:10 PM	12:20 PM	Q&A			
12:20 PM	12:50 PM	**Room 1: Award Ceremony**	Chaired by Dereje Agonafer	Allan Kraus Thermal Management Medalist	University of Texas at Arlington
12:50 PM	1:50 PM		Chaired by Baris Dogruoz	Other Awards Ceremony: Intel Best Paper Award	Maxar Technologies
Room 1: Tutorial Chaired by Jungwan Cho (Sungkyunkwan University)					
1:50 PM	3:40 PM	Tutorial	Ashutosh Giri, Ronald Warzoha, Ankur Jain	Nanoscale Thermal Metrology for Solid Materials in Electronics Packaging	University of Rhode Island, US Naval Academy, University of Texas at Arlington
3:40 PM	3:50 PM	Q&A			
Day 4 - Monday, 1st November 2021					
InterPACK Organization Zoom Meetings					
11:00 AM	12:00 PM	InterPACK Summary and Planning Meeting			
12:00 PM	1:00 PM	InterPACK Advisory Committee (By Invitation Only)			